

Quarterly Reliability Monitoring Results

Quarters: Q1/2021 to Q4/2021

| Based on structural | similarity |
|---------------------|------------|
|---------------------|------------|

| Supplier | | User Part Number | | | | | | |
|---|------------------------------------|--|-----------------------|-----------|------------|-----------|--|--|
| Nexperia B.V. | | PDTC144VT | | | | | | |
| Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test | | Part Description | | | | | | |
| | | Nexperia DHAM Small Signal Bipolar Transistor | | | | | | |
| | | SMD package | | | | | | |
| | | Test Conditions | Duration | # Lots | # Quantity | # Rejects | | |
| | TEST | | | | | | | |
| | Pre- and Post-Stress | | | | | | | |
| # E1 | Electrical Test | Tamb = 25 °C | N/A | see below | all parts | see below | | |
| | | JESD22-A113 | 241 | | | | | |
| | PC | Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% | 24 hours 168 hours | | | | | |
| # A1 | Preconditioning | Reflow soldering | 3 cycles | 849 | 61170 | 0 | | |
| # 11 | | MIL-STD-750-1 | , | 049 | 011/0 | 0 | | |
| | HTRB | M1039 Method A | | | | | | |
| | | Tj = Tjmax, Vr = 100% of max. datasheet | | | | | | |
| # B1 | Bias | reverse voltage | 1000 hours | 202 | 16160 | 0 | | |
| | | | | | | | | |
| | тс | JESD22-A104 | | | | | | |
| # A4 | Temperature Cycling | -65 °C to Tjmax, not to exceed 150°C | 1000 cycles | 171 | 13680 | 0 | | |
| | | JESD22-A102 | | | | | | |
| | AC | Tamb = 121 °C, RH = 100 % | | | | | | |
| # A3 alt | Autoclave | Pressure = 205 kPa (29.7 psia) | 96 hours | 173 | 13840 | 0 | | |
| | | JESD22-A101 | | | | | | |
| | H3TRB High Humidity High | Tamb = $85 ^{\circ}$ C, RH = 85% , VR = 80% of | | | | | | |
| # A2 alt | Temperature Reverse Bias | | 1000 hours | 173 | 13840 | 0 | | |
| # AZ dll | | MIL-STD-750 Method 1037 | 1000 110013 | 175 | 13040 | 0 | | |
| | IOL | ton = toff, devices powered to insure ΔT_j = | | | | | | |
| # A5 | Intermittent Operating Life | | 1000 hours | 197 | 15760 | 0 | | |
| | | · · | 2000 110010 | | | - | | |
| | RSH | JESD22-A111 | | | | | | |
| # C8 | Resistance to Solder Heat | 260 °C ± 5 °C | 10 s | 135 | 4050 | 0 | | |
| | SD | | | | | | | |
| # C10 | Solderability | J-STD-002 | | 342 | 3420 | 0 | | |

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|------------------|------------------------------------|----------|---------|--------------------|------------|
| Nexperia DHAM | Small Signal Bipolar Transistor | 16160 | 0 | 0.26 | 3.81E+09 |

© 2022 Nexperia B.V.

All information hereunder is per Nexperia's best knowledge. This document does not provide for any nexperia.com representation or warranty express or implied by Nexperia. In case Nexperia has tested the product, this documentation reflects the outcome of the analysis of the actually tested parts only.